









Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 099 FR4 55 L41.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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| Layers | in μ | Material | Build-Up | Assembly |
|-----------------|-----------|----------|--|------------------------|
| Layer-1 | 55 μ | Copper |  | } A1 } B |
| | 100 μ | Prepreg | (100 μ PrePreg-Type: 2125) | |
| | 100 μ | Prepreg |  | |
| Layer-2 | 35 μ | Copper |  | |
| | 410 μ | L-FR4 |  | |
| Layer-3 | 35 μ | Copper |  | |
| | 100 μ | Prepreg |  | |
| | 100 μ | Prepreg |  | |
| Layer-99 | 55 μ | Copper |  | |

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